

1.5V Drive Pch+SBD MOSFET

ES6U1

●Structure

Silicon P-channel MOSFET / Schottky barrier diode

Features

- 1) Pch MOSFET and schottky barrier diode are put in WEMT6 package.
- 2) High-speed switching, Low On-resistance.
- 3) Low voltage drive (1.5V drive).
- 4) Built-in Low VF schottky barrier diode.

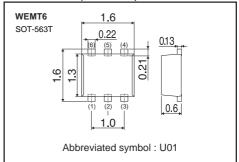
Application

Switching

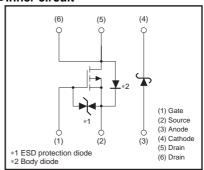
Packaging specifications

| | Package | Taping |
|-------|------------------------------|--------|
| Type | Code | T2R |
| | Basic ordering unit (pieces) | 8000 |
| ES6U1 | | 0 |

●Dimensions (Unit: mm)



•Inner circuit



● Absolute maximum ratings (Ta=25°C)

<MOSFET>

| WOOTET? | | | | | | | |
|----------------------|------------|--------------------|------|-------------|--|--|--|
| Parameter | Symbol | Limits | Unit | | | | |
| Drain-source voltage | | V_{DSS} | -12 | V | | | |
| Gate-source voltage | | V _{GSS} | ±10 | V | | | |
| Drain aussant | Continuous | lσ | ±1.3 | А | | | |
| Drain current | Pulsed | I _{DP} *1 | ±2.6 | А | | | |
| Source current | Continuous | Is | -0.5 | А | | | |
| (Body diode) | Pulsed | I _{SP} *1 | -2.6 | А | | | |
| Channel temperature | | Tch | 150 | °C | | | |
| Power dissipation | | P _D *2 | 0.7 | W / ELEMENT | | | |

<Di>

| Parameter | Symbol | Limits | Unit | |
|---------------------------------|---------------------|--------|-------------|--|
| Repetitive peak reverse voltage | VRM | 25 | V | |
| Reverse voltage | VR | 20 | V | |
| Forward current | lF | 0.5 | A | |
| Forward current surge peak | I _{FSM} *1 | 2.0 | Α | |
| Junction temperature | Tj | 150 | °C | |
| Power dissipation | P _D *2 | 0.5 | W / ELEMENT | |

<MOSFET and Di>

| Parameter | Symbol | Limits | Unit | |
|------------------------------|------------------|-------------|-----------|--|
| Power dissipation | P _D * | 0.8 | W / TOTAL | |
| Range of storage temperature | Tstg | -55 to +150 | °C | |

^{*} Mounted on a ceramic board

^{*1} Pw≤10μs, Duty cycle≤1% *2 Mounted on a ceramic board

^{*1 60}Hz • 1 cycle *2 Mounted on a ceramic board

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●Electrical characteristics (Ta=25°C)

<MOSFET>

| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|---------------------------------|-----------------------|------|------|------|------|---|
| Gate-source leakage | Igss | - | _ | ±10 | μА | Vgs= ±10V, Vps=0V |
| Drain-source breakdown voltage | V _(BR) DSS | -12 | _ | _ | V | I _D = -1mA, V _G S=0V |
| Zero gate voltage drain current | IDSS | _ | _ | -1 | μА | V _{DS} = -12V, V _{GS} =0V |
| Gate threshold voltage | V _{GS (th)} | -0.3 | - | -1.0 | V | $V_{DS} = -6V$, $I_{D} = -1mA$ |
| | | - | 190 | 260 | mΩ | I _D = -1.3A, V _G S= -4.5V |
| Static drain-source on-state | Dog ()* | _ | 280 | 390 | mΩ | I _D = -0.6A, V _G S= -2.5V |
| resistance | RDS (on) | - | 400 | 600 | mΩ | I _D = -0.6A, V _G S= -1.8V |
| | | - | 530 | 1060 | mΩ | I _D = -0.2A, V _G S= -1.5V |
| Forward transfer admittance | Y _{fs} * | 1.4 | _ | _ | S | V _{DS} = -6V, I _D = -1.3A |
| Input capacitance | Ciss | _ | 290 | _ | pF | V _{DS} = -6V |
| Output capacitance | Coss | - | 28 | _ | pF | V _{GS} = 0V |
| Reverse transfer capacitance | Crss | _ | 21 | _ | pF | f= 1MHz |
| Turn-on delay time | t _{d (on)} * | - | 8 | _ | ns | Vpp≒-6V |
| Rise time | tr * | _ | 10 | _ | ns | ID= -0.6A |
| Turn-off delay time | td (off) * | _ | 30 | _ | ns | VGS= −4.5V RL≒10Ω |
| Fall time | t _f * | _ | 9 | _ | ns | R _G = 10Ω |
| Total gate charge | Qg * | _ | 2.4 | _ | nC | V _{DD} ≒−6V R _L ≒4.6Ω |
| Gate-source charge | Q _{gs} * | _ | 0.6 | _ | nC | $I_D=-1.3A$ $R_G=10\Omega$ |
| Gate-drain charge | Q _{gd} * | _ | 0.4 | _ | nC | V _{GS} = -4.5V |

^{*}Pulsed

<MOSFET> Body diode (Source-drain)

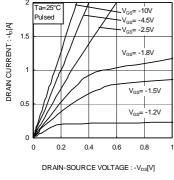
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|-----------------|--------|------|------|------|------|---|
| Forward voltage | Vsp * | _ | _ | -1.2 | V | I _S = -1.3A, V _{GS} =0V |
| *Pulsed | | | | | | |

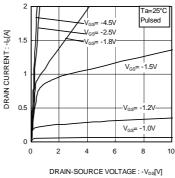
<Di>

| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|-----------------|--------|------|------|------|------|-----------------------|
| Forward voltage | VF | _ | _ | 0.36 | V | I _F = 0.1A |
| | | _ | _ | 0.52 | V | I _F = 0.5A |
| Reverse current | IR | _ | _ | 100 | μΑ | V _R = 20V |

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•Electrical characteristics curves





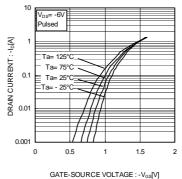
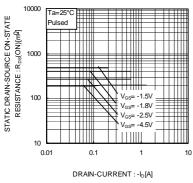
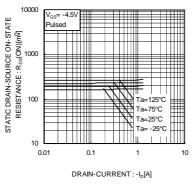


Fig.1 Typical Output Characteristics(I)

Fig.2 Typical Output Characteristics(${\rm I\hspace{-.1em}I}$)

Fig.3 Typical Transfer Characteristics





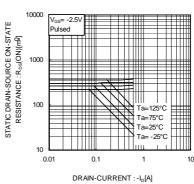
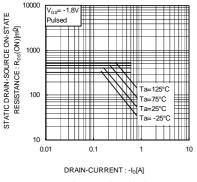
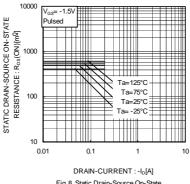


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(Ⅲ)





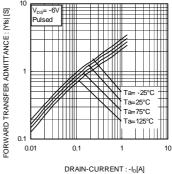
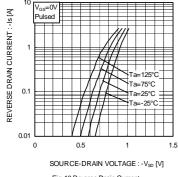


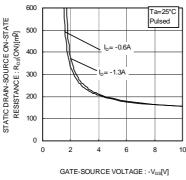
Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(V)

Fig.9 Forward Transfer Admittance vs. Drain Current

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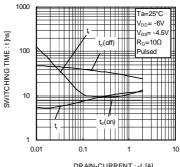
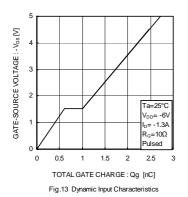
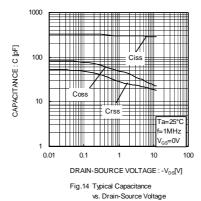


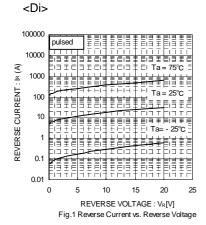
Fig.10 Reverse Drain Current vs. Sourse-Drain Voltage Resistance vs

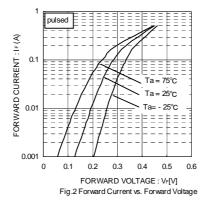
Fig.11 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

DRAIN-CURRENT : -I_D[A]
Fig.12 Switching Characteristics









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Measurement circuits

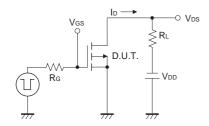


Fig.1-1 Switching Time Measurement Circuit

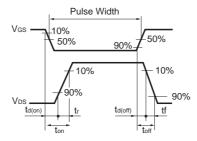


Fig.1-2 Switching Waveforms

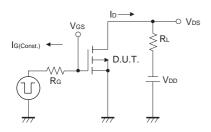
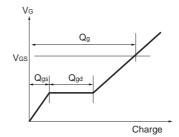


Fig.2-1 Gate Charge Measurement Circuit



Flg.2-2 Gate Charge Waveform

Notice

- 1. SBD has a large reverse leak current compared to other type of diode. Therefore; it would raise a junction temperature, and increase a reverse power loss. Further rise of inside temperature would cause a thermal runaway.

 This built-in SBD has low VF characteristics and therefore, higher leak current. Please consider enough the surrounding temperature, generating heat of MOSFET and the reverse current.
- 2. This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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